Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	6	("20030019755"|"20030075450"|"6210555").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 11:37
S2	1	("205"/$.ccls. "204"/$.ccls.) and (electrolysis electrolytic electrochemic$4 electrodeposit$5 electroplat$5) and (surfactant wetting carrier suppressor suppresser) and (brighten$4 accelerator) and (dielectric near10 (opening hole via "through-hole")) and (dielectric insulat$3) and (trench microvia recess$3 "through-hole" "thru-hole" opening hole via) and (((revers$4 forward cathodic pulse period$4) near10 current)) and ((board printed) near4 circuit) and (aspect adj ratio) same (hole adj diameter)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 11:39
S3	1	("205"/$.ccls. "204"/$.ccls.) and (electrolysis electrolytic electrochemic$4 electrodeposit$5 electroplat$5) and (surfactant wetting carrier suppressor suppresser) and (brighten$4 accelerator) and (dielectric insulat$3) and (trench microvia recess$3 "through-hole" "thru-hole" opening hole via) and (((revers$4 forward electrodeposition cathodic pulse period$4) near10 current)) and ((board printed) near4 circuit) and (aspect adj ratio) same (hole adj diameter) and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 11:41
S4	30	("205"/$.ccls. "204"/$.ccls.) and (electrolysis electrolytic electrochemic$4 electrodeposit$5 electroplat$5) and (surfactant wetting carrier suppressor suppresser) and (brighten$4 accelerator)and (dielectric insulat$3) and (trench microvia recess$3 "through-hole" "thru-hole" opening hole via) and (((revers$4 forward electrodeposition cathodic pulse period$4) near10 current)) and ((board printed) near4 circuit) and (aspect adj ratio) and (diameter) and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 11:54

S5	12	("205"/$.ccls. "204"/$.ccls.) and (electrolysis electrolytic electrochemic$4 electrodeposit$5 electroplat$5) and (surfactant wetting carrier suppressor suppresser) and (brighten$4 accelerator)and (dielectric insulat$3) and (trench microvia recess$3 "through-hole" "thru-hole" opening hole via) and (((revers$4 forward electrodeposition cathodic pulse period$4) near10 current)) and ((board printed) near4 circuit) and (aspect adj ratio) and (diameter) and copper and ((off adj2 time) (rest adj2 time) (zero adj2 current) pause)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 11:51
S6	114	("205"/$.ccls. "204"/$.ccls.) and (electrolysis electrolytic electrochemic$4 electrodeposit$5 electroplat$5) and (surfactant wetting carrier suppressor suppresser) and (brighten$4 accelerator) and (trench microvia recess$3 "through-hole" "thru-hole" opening hole via) and (((revers$4 forward electrodeposition cathodic pulse period$4) near10 current)) and ((board printed) near4 circuit) and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 11:55
S7	33	("205"/$.ccls. "204"/$.ccls.) and (electrolysis electrolytic electrochemic$4 electrodeposit$5 electroplat$5) and (surfactant wetting carrier suppressor suppresser) and (brighten$4 accelerator) and (trench microvia recess$3 "through-hole" "thru-hole" opening hole via) and (((revers$4 forward electrodeposition cathodic pulse period$4) near10 current)) and ((board printed) near4 circuit) and copper and ((off adj2 time) (rest adj2 time) (zero adj2 current) pause)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 14:02

S8	20	("205"/$.ccls. "204"/$.ccls.) and (electrolysis electrolytic electrochemic$4 electrodeposit$5 electroplat$5) and (surfactant wetting carrier suppressor suppresser) and (brighten$4 accelerator) and (trench microvia recess$3 "through-hole" "thru-hole" opening hole via) and (((revers$4 forward electrodeposition cathodic pulse period$4) near10 current)) and ((board printed) near4 circuit) and copper and ((off adj2 time) (rest adj2 time) (zero adj2 current) pause) and (dielectric insulat$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 12:08
S9	25	("205"/$.ccls. "204"/$.ccls.) and (electrolysis electrolytic electrochemic$4 electrodeposit$5 electroplat$5) and (surfactant wetting carrier suppressor suppresser) and (brighten$4 accelerator) and (trench microvia recess$3 "through-hole" "thru-hole" opening hole via) and (((revers$4 forward electrodeposition cathodic pulse period$4) near10 current)) and ((board printed) near4 circuit) and copper adj sulfate and ((off adj2 time) (rest adj2 time) (zero adj2 current) pause)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 14:03
S10	25	("205"/$.ccls. "204"/$.ccls.) and (electrolysis electrolytic electrochemic$4 electrodeposit$5 electroplat$5) and (surfactant wetting carrier suppressor suppresser) and (brighten$4 accelerator) and (trench microvia recess$3 "through-hole" "thru-hole" opening hole via) and (((revers$4 forward electrodeposition cathodic pulse period$4) near10 current)) and ((board printed) near4 circuit) and copper adj sulfate and ((off adj2 time) (rest adj2 time) (zero near3 current) pause)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 14:33

S11	13	("205"/$.ccls. "204"/$.ccls.) and (electrolysis electrolytic electrochemic$4 electrodeposit$5 electroplat$5) and (trench microvia recess$3 "through-hole" "thru-hole" opening hole via) and (((revers$4 forward electrodeposition cathodic pulse period$4) near10 current)) and ((board printed) near4 circuit) and copper adj sulfate and ((off adj2 time) (rest adj2 time) (zero near3 current) pause) not S10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 14:34
S12	13	("205"/$.ccls. "204"/$.ccls.) and (electrolysis electrolytic electrochemic$4 electrodeposit$5 electroplat$5) and ("through-hole" "thru-hole" opening hole via) and (((revers$4 forward electrodeposition cathodic pulse period$4) near10 current)) and ((board printed) near4 circuit) and copper adj sulfate and ((off adj2 time) (rest adj2 time) (zero near3 current) pause) not S10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 14:44
S13	19	("205"/$.ccls. "204"/$.ccls.) and (electrolysis electrolytic electrochemic$4 electrodeposit$5 electroplat$5) and ("through-hole" "thru-hole" hole via) and (((revers$4 forward electrodeposition cathodic pulse period$4) near10 current step) ((positive$3) near10 (pulse step))) and ((board printed) near4 circuit) and copper adj sulfate and ((off adj2 time) (rest adj2 time) (zero near3 current) pause) not S10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 14:54
S14	30	(electrochemic$4 electrodeposit$5 electroplat$5) and ("through-hole" "thru-hole" hole via) and (((revers$4 forward electrodeposition cathodic pulse period$4) near5 current step) ((positive$3 negative$2) near5 (pulse step))) and ((board printed) near4 circuit) and copper adj sulfate and ((off adj2 time) (rest adj2 time) (zero near3 current) pause) not S10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 14:54

S15	24	("205"/$.ccls. "204"/$.ccls.) and (electrochemic$4 electrodeposit$5 electroplat$5) and ("through-hole" "thru-hole" hole) and (((revers$4 forward electrodeposition cathodic pulse period$4) near5 current step) ((positive$3 negative$2) near5 (pulse step))) and ((board printed) near4 circuit) and copper adj sulfate and ((off adj2 time) (rest adj2 time) (zero near3 current) pause) and (aspect adj ratio) and (diameter)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 14:56
S16	86	("205"/$.ccls. "204"/$.ccls.) and (electrochemic$4 electrodeposit$5 electroplat$5) and ("through-hole" "thru-hole" hole) and (((revers$4 forward electrodeposition cathodic pulse period$4) near5 current step) ((positive$3 negative$2) near5 (pulse step))) and ((board printed) near4 circuit) and copper adj sulfate and (aspect adj ratio) and (diameter) not S15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 14:58
S17	86	("205"/$.ccls. "204"/$.ccls.) and (electrochemic$4 electrodeposit$5 electroplat$5) and ("through-hole" "thru-hole" hole) and (((revers$4 forward electrodeposition cathodic pulse period$4) near5 current step) ((positive$3 negative$2) near5 (pulse step))) and ((board printed) near4 circuit) and copper adj sulfate and (aspect adj ratio) and (diameter) not S15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/04 14:58